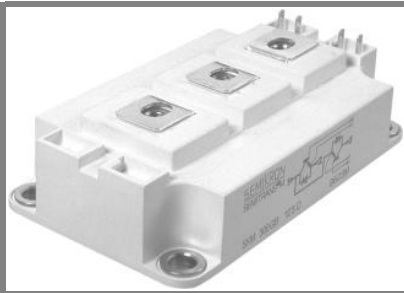


# SKM 150GB12T4G



SEMITRANS® 3

## IGBT4 Modules

### SKM 150GB12T4G

#### Target Data

#### Features

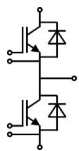
- IGBT4 = 4. Generation (Trench) IGBT
- $V_{CEsat}$  with positive temperature coefficient
- High short circuit capability, self limiting to  $6 \times I_{CNOM}$
- Soft switching 4. Generation CAL diode (CAL4)

#### Typical Applications

- AC inverter drives
- UPS
- Electronic welders at  $f_{sw}$  up to 20 kHz

#### Remarks

- Case temperature limited to  $T_c = 125^\circ\text{C}$  max, recomb.  $T_{op} = -40 \dots +150^\circ\text{C}$ , product rel. results valid for  $T_j \leq 150^\circ$

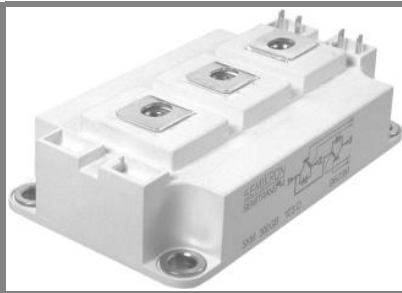


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Absolute Maximum Ratings		$T_c = 25^\circ\text{C}$ , unless otherwise specified		
Symbol	Conditions	Values		Units
<b>IGBT</b>				
$V_{CES}$	$T_j = 25^\circ\text{C}$	1200		V
$I_C$	$T_j = 175^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	220	A
		$T_{case} = 80^\circ\text{C}$	170	A
$I_{CRM}$	$I_{CRM} = 3 \times I_{CNOM}$	450		A
$V_{GES}$		$\pm 20$		V
$t_{psc}$	$V_{CC} = 800\text{ V}; V_{GE} \leq 15\text{ V}; T_j = 150^\circ\text{C}$ $V_{CES} < 1200\text{ V}$	10		$\mu\text{s}$
<b>Inverse Diode</b>				
$I_F$	$T_j = 175^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	180	A
		$T_{case} = 80^\circ\text{C}$	135	A
$I_{FRM}$	$I_{FRM} = 3 \times I_{FNOM}$	450		A
$I_{FSM}$	$t_p = 10\text{ ms}; \sin.$	$T_j = 175^\circ\text{C}$	860	A
<b>Module</b>				
$I_{t(RMS)}$		500		A
$T_{vj}$		-40 ... +175		$^\circ\text{C}$
$T_{stg}$		-40 ... +125		$^\circ\text{C}$
$V_{isol}$	AC, 1 min.	4000		V

Characteristics		$T_c = 25^\circ\text{C}$ , unless otherwise specified				
Symbol	Conditions	min.	typ.	max.	Units	
<b>IGBT</b>						
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 6\text{ mA}$	5	5,8	6,5	V	
$I_{CES}$	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$	$T_j = 25^\circ\text{C}$			mA	
$V_{CE0}$		$T_j = 25^\circ\text{C}$		0,8	0,9	V
		$T_j = 150^\circ\text{C}$		0,7	0,8	V
$r_{CE}$	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$			m $\Omega$	
		$T_j = 150^\circ\text{C}$			m $\Omega$	
$V_{CE(sat)}$	$I_{Cnom} = 150\text{ A}, V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$		1,85	2,05	V
		$T_j = 150^\circ\text{C}_{chiplev.}$		2,25	2,45	V
$C_{ies}$	$V_{CE} = 25, V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$		9,3		nF
$C_{oes}$				0,58		nF
$C_{res}$				0,51		nF
$Q_G$	$V_{GE} = -8\text{ V} / +15\text{ V}$			850		nC
$R_{Gint}$	$T_j = 25^\circ\text{C}$			5		$\Omega$
$t_{d(on)}$	$R_{Gon} = \Omega$	$V_{CC} = 600\text{ V}$ $I_C = 150\text{ A}$				ns
$t_r$					14,8	ns
$E_{on}$						mJ
$t_{d(off)}$	$R_{Goff} = \Omega$	$T_j = 150^\circ\text{C}$ $V_{GE} = \pm 15\text{ V}$				ns
$t_f$						ns
$E_{off}$					14,8	mJ
$R_{th(j-c)}$	per IGBT			0,2		K/W

# SKM 150GB12T4G



SEMITRANS® 3

## IGBT4 Modules

### SKM 150GB12T4G

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- $V_{CEsat}$  with positive temperature coefficient
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#### Remarks

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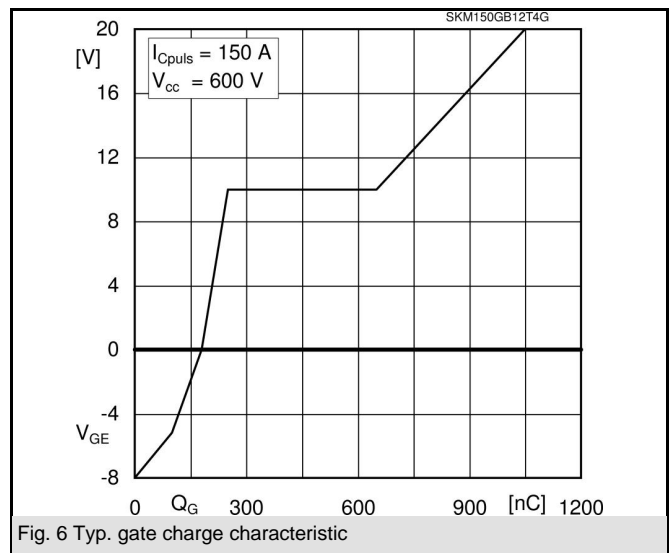
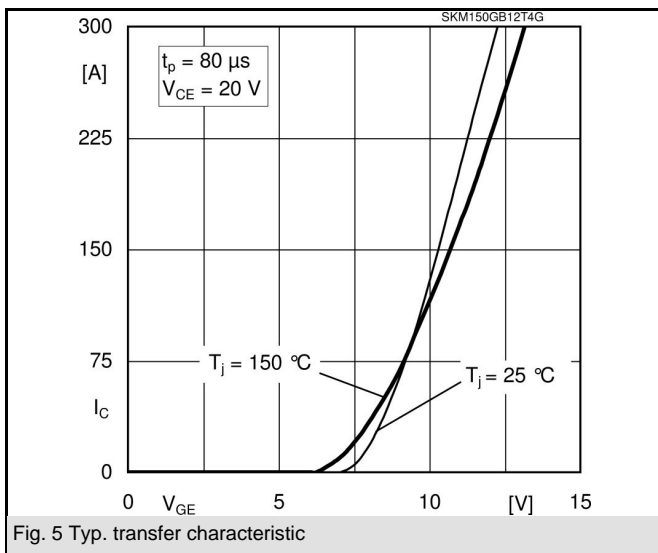
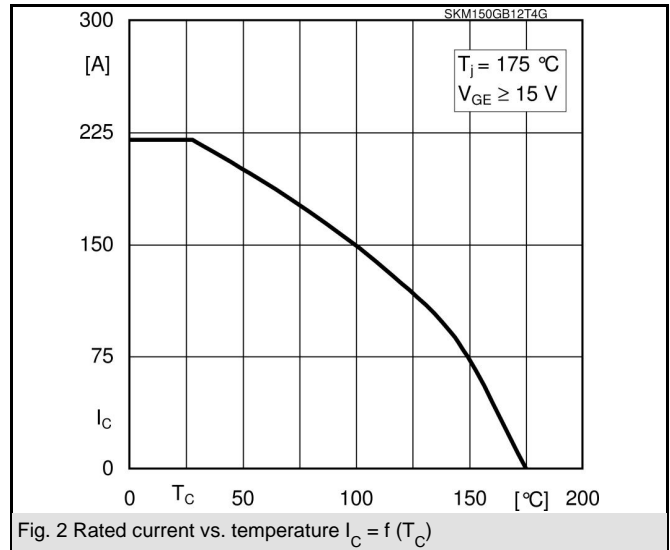
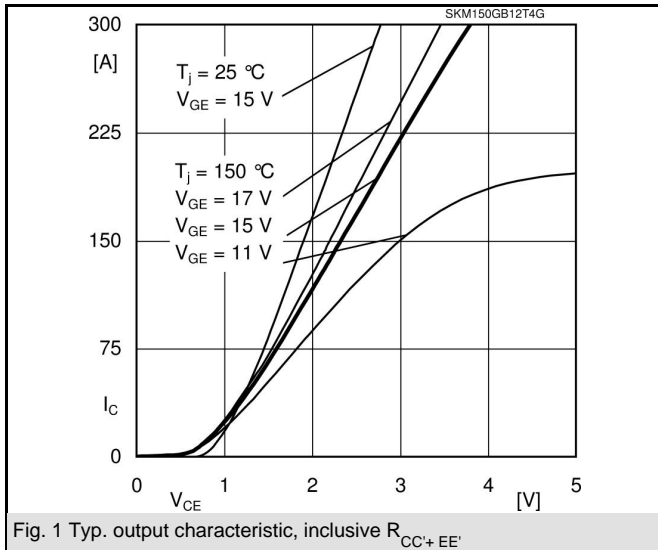
Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
<b>Inverse Diode</b>					
$V_F = V_{EC}$	$I_{Fnom} = 150 \text{ A}; V_{GE} = 0 \text{ V}$				
			$T_j = 25^\circ\text{C}_{chiplev.}$	2,2	2,5
			$T_j = 150^\circ\text{C}_{chiplev.}$	2,1	2,45
$V_{F0}$			$T_j = 25^\circ\text{C}$	1,3	1,5
			$T_j = 150^\circ\text{C}$	0,9	1,1
$r_F$			$T_j = 25^\circ\text{C}$	6	6,67
			$T_j = 150^\circ\text{C}$	8	9
$I_{RRM}$	$I_F = 150 \text{ A}$		$T_j = 150^\circ\text{C}$		A
$Q_{rr}$					$\mu\text{C}$
$E_{rr}$	$V_{GE} = -15\text{V}$			11,3	mJ
$R_{th(j-c)}$	per diode			0,32	K/W
<b>Freewheeling Diode</b>					
$V_F = V_{EC}$	$I_{Fnom} = \text{A}; V_{GE} = \text{V}$		$T_j = ^\circ\text{C}_{chiplev.}$		V
$V_{F0}$			$T_j = ^\circ\text{C}$		V
$r_F$			$T_j = ^\circ\text{C}$		V
$I_{RRM}$	$I_F = \text{A}$		$T_j = ^\circ\text{C}$		A
$Q_{rr}$					$\mu\text{C}$
$E_{rr}$					mJ
	per diode				K/W
<b>Module</b>					
$L_{CE}$				15	20
$R_{CC'+EE'}$	res., terminal-chip		$T_{case} = 25^\circ\text{C}$		0,35
			$T_{case} = 125^\circ\text{C}$		0,5
$R_{th(c-s)}$	per module			0,02	0,038
$M_s$	to heat sink M6			3	5
$M_t$	to terminals M6			2,5	5
w					325
					g

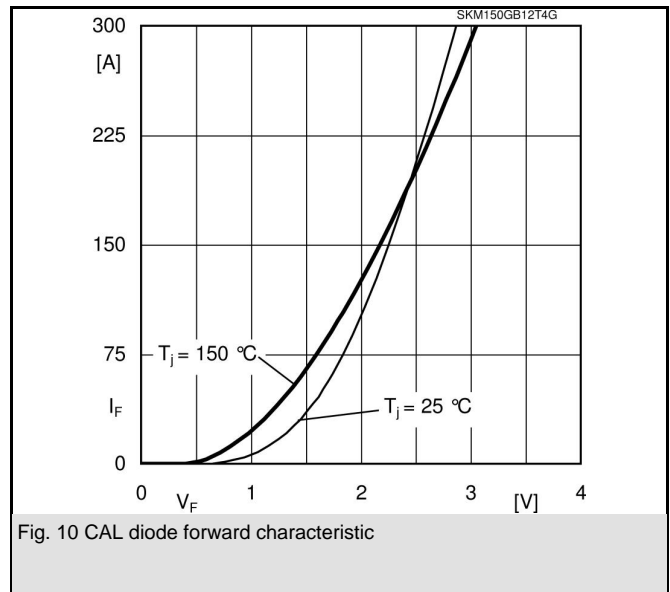
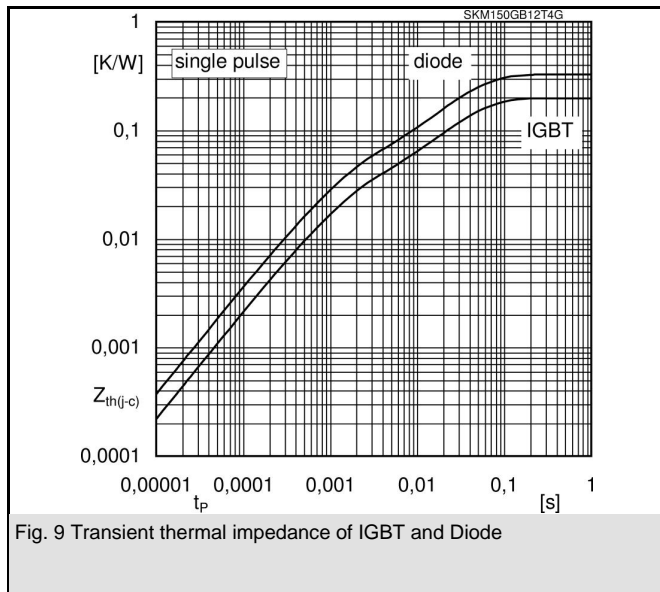
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.



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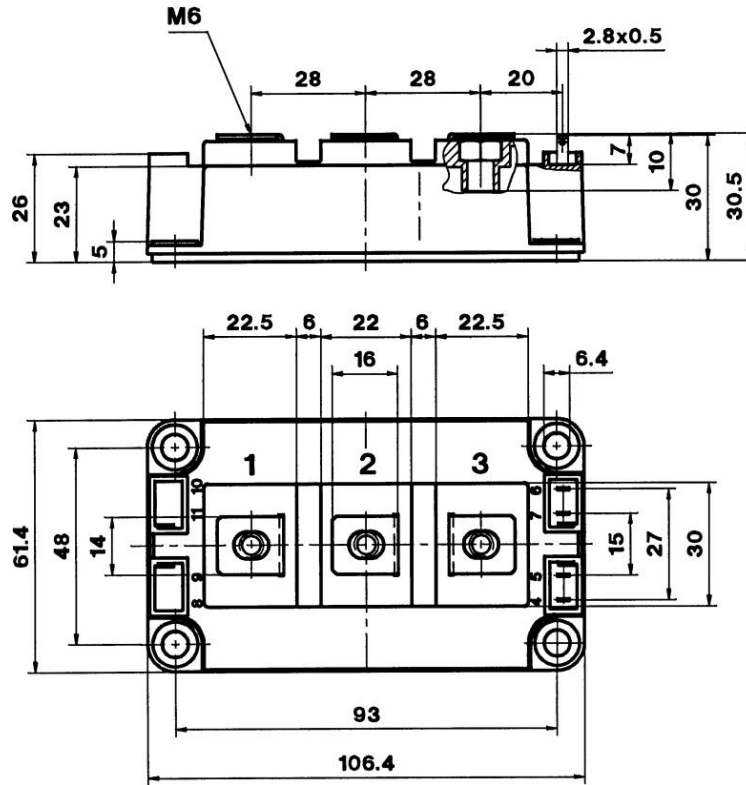


# SKM 150GB12T4G

UL recognized file

CASED56

no. E 63 532



Case D56

